



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-02-23
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STL130N6F7	BSER*OD6DTC2	A	SHENZHEN B/E	2016-02-23
	Amount	UoM	Unit type	ST ECOPACK Grade
	69.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5, 6, 0.8	12	FLAT	
Comment	Power FLAT 5x6 8L SINGLE			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BSER*OD6DTC2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.038	mg	supplier	die	Silicon (Si)	7440-21-3		0.921	mg	887175	13333
				supplier	metallization	Aluminium (Al)	7429-90-5		0.041	mg	39537	594
				supplier	Passivation	Silicon Nitride	12033-89-5		0.018	mg	17358	261
				supplier	Passivation	Silicon Oxide	7631-86-9		0.017	mg	16393	246
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	1929	29
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.029	mg	27965	420
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.010	mg	9643	145
Leadframe	Copper & its alloys	49.036	mg	supplier	alloy	Copper (Cu)	7440-50-8		47.785	mg	974488	692536
				supplier	alloy	Iron (Fe)	7439-89-6		1.124	mg	22922	16290
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.068	mg	1387	986
				supplier	alloy	Zinc (Zn)	7440-66-6		0.059	mg	1203	855
Soft solder	Solder	3.916	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.622	mg	924923	52493
				supplier	solder	Tin (Sn)	7440-31-5		0.098	mg	25026	1420
				supplier	solder	Silver (Ag)	7440-22-4		0.196	mg	50051	2841
Bonding wires	Other inorganic materials	0.116	mg	supplier	wire	Gold (Au)	7440-57-5		0.116	mg	1000000	1681
				supplier	mold compound	Silica, vitreous	60676-86-0		5.845	mg	926161	84710
				supplier	mold compound	epoxy resin	85954-11-6		0.252	mg	39930	3652
				supplier	mold compound	phenol resin	26834-02-6		0.189	mg	29948	2739
Encapsulation	Other Organic Materials	6.311	mg	supplier	mold compound	carbon black	1333-86-4		0.025	mg	3961	362
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.149	mg	1000000	2159
Connections coating	Solder	0.149	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.149	mg	1000000	2159
Clip		8.434	mg	supplier	alloy	Copper (Cu)	7440-50-8		8.434	mg	1000000	122232